



PRODUCT BULLETIN # 16609

Issue Date: 29-Mar-2011

TITLE: Mold Compound Conversion for High Voltage MOSFET TO-220FP Devices

PROPOSED FIRST SHIP DATE: 29-Mar-2011

AFFECTED CHANGE CATEGORY(S): Halide-Free Mold Compound Conversion

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or Jason Jeong < Jason.Jeong@onsemi.com >

DESCRIPTION AND PURPOSE:

This change will only affect the molding compound of High Voltage MOSFET TO-220FP devices. The halide-free Samsung SG-8300HKL mold compound will replace the current MP-4000H6 mold compound. No other changes are made in terms of wafer processing and assembly, and there will be no change in the electrical performance of the products.

List of affected General Parts:

NDF02N60ZG
NDF03N60ZG
NDF04N60ZG
NDF04N62ZG
NDF05N50ZG
NDF06N60ZG
NDF06N62ZG
NDF08N50ZG
NDF08N60ZG
NDF10N60ZG
NDF10N62ZG
NDF11N50ZG